

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L11	22856	(die ic chip) and (wafer substrate board carrier) and fuse	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/1 0 16:25	
2	BRS	L12	6845	(die ic chip) and (wafer substrate board carrier) same fuse	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/1 0 16:26	
3	BRS	L13	1648	(die ic chip) and (wafer substrate board carrier) same fuse and (scribe alignment adj mark mark groove)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/1 0 16:30	
4	BRS	L14	251	(die ic chip) and (wafer substrate board carrier) same fuse same (scribe alignment adj mark mark groove)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2004/12/1 0 16:38	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L22	570	257/209	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:20	
6	BRS	L23	222	257/209 and (die ic chip) and (substrate board carrier wafer) and (electrode pad)	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:23	
7	BRS	L24	128	257/209 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:32	
8	BRS	L25	303	257/529 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:43	
9	BRS	L26	142	438/132 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:53	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	L27	26	438/462 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:55	
11	BRS	L29	84	438/467 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:56	
12	BRS	L30	123	438/601 and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:56	
13	BRS	L28	840	"438"/\$.ccls. and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:57	
14	BRS	L31	68	"438"/\$.ccls. and (die ic chip) and (substrate board carrier wafer) and (electrode pad) and fuse and scribe	USPAT; EPO; JPO; DERWE NT; IBM_T DB	2004/12/10 17:58	